



Click [here](#) for the 3D model.

### Dimensions

Case Code	20
L	7.9mm +/-0.38mm
W	6.1mm +/-0.4mm
H	8.9mm +/-0.38mm
S	1.4mm +/-0.38mm
F	4.1mm +/-0.2mm
K	6.6mm +/-0.38mm

### Packaging Specifications

Packaging	T&R, 178mm
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### General Information

Series	TSP
Dielectric	Polymer Tantalum
Style	Stacked Chip
Description	SMD, Polymer, KO, Stacks, High Reliability
Features	High Reliability
RoHS	No
Prop 65	<b>⚠ WARNING:</b> Cancer and reproductive harm - <a href="http://www.p65warnings.ca.gov">http://www.p65warnings.ca.gov</a> .
SCIP Number	30e82d35-b509-48ec-8c77-2d5ec01b3abc
Termination	Solder Coated
Termination (Stack)	Solder Coated
AEC-Q200	No

### Specifications

Capacitance	940 uF
Capacitance Tolerance	20%
Voltage DC	16 VDC (105C), 10.72 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	105°C
Dissipation Factor	10% 120Hz 25C
Failure Rate	N/A
Resistance	25 mOhms (100kHz 25C)
Leakage Current	1504 uA (5min 25°C)
Testing and Reliability	4 Cycles At +25C +/-5C